A B S T R A C T

The invention provides a method of fabricating a plurality of chips, each chip comprising at least one circuit, the method comprising the following steps in succession:

- creating chips on a layer of semiconductor material, said layer being integral with a substrate;
- transferring said layer including the chips from the substrate to a support; and
- forming individual chips by cutting said layer in accordance with a predetermined cutting pattern;

the method being characterized in that, prior to transferring the layer onto the support, it also comprises forming a weakening pattern corresponding to the cutting pattern on the support. The invention also concerns a method of fabricating an associated support, and said support.